

To all our customers

Regarding the change of names mentioned in the document, such as Hitachi Electric and Hitachi XX, to Renesas Technology Corp.

The semiconductor operations of Mitsubishi Electric and Hitachi were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Hitachi, Hitachi, Ltd., Hitachi Semiconductors, and other Hitachi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Renesas Technology Home Page: <http://www.renesas.com>

Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corporation product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corporation or a third party.
2. Renesas Technology Corporation assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.

3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corporation or an authorized Renesas Technology Corporation product distributor for the latest product information before purchasing a product listed herein.

The information described here may contain technical inaccuracies or typographical errors.

Renesas Technology Corporation assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.

Please also pay attention to information published by Renesas Technology Corporation by various means, including the Renesas Technology Corporation Semiconductor home page (<http://www.renesas.com>).

4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corporation assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
5. Renesas Technology Corporation semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corporation or an authorized Renesas Technology Corporation product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
6. The prior written approval of Renesas Technology Corporation is necessary to reprint or reproduce in whole or in part these materials.
7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
8. Please contact Renesas Technology Corporation for further details on these materials or the products contained therein.

HD74LS95B ● 4-bit Parallel Access Shift Registers

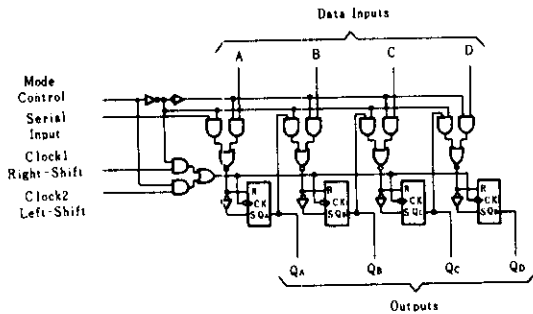
This 4-bit register features parallel and serial inputs, parallel outputs, mode control, and two clock inputs. The register has three mode operation:

- Parallel (broadside) load
- Shift right (the direction Q_A toward Q_D)
- Shift left (the direction Q_D toward Q_A)

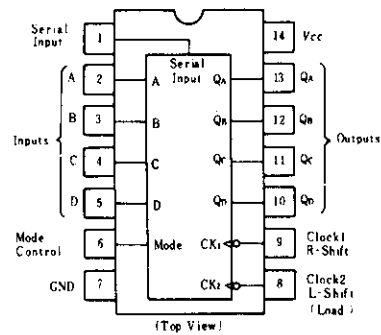
Parallel loading is accomplished by applying the four bits of data and taking the mode control input high. The data is loaded into the associated flip-flops and appears at the outputs after the high-to-low transition of the clock-2 input. During loading, the entry of serial data is inhibited. Shift right is accomplished on the high-to-low transition of clock-1 when the

mode control is low; shift left is accomplished on the high-to-low transition of clock-2 when the mode control is high by connecting the output of each flip-flop to the parallel input of the previous flip-flop (Q_D to input C, etc.) and serial data is entered at input D. The clock input may be applied commonly to clock-1 and clock-2 if both modes can be clocked from the same source. Changes at the mode control input should normally be made while both clock inputs are low; however, conditions described in the last three lines of the function table will also ensure that register contents are protected.

■ BLOCK DIAGRAM



■ PIN ARRANGEMENT



■ FUNCTION TABLE

Mode Control	Inputs							Outputs			
	Clocks		Serial	Parallel				Q_A	Q_B	Q_C	Q_D
	2(L)	1(H)		A	B	C	D				
H	H	X	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
H	↓	X	X	a	b	c	d	a	b	c	d
H	↓	X	X	Q_B^\dagger	Q_C^\dagger	Q_D^\dagger	d	Q_{Bn}	Q_{Cn}	Q_{Dn}	d
L	L	H	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
L	X	↓	H	X	X	X	X	H	Q_{An}	Q_{Bn}	Q_{Cn}
L	X	↓	L	X	X	X	X	L	Q_{An}	Q_{Bn}	Q_{Cn}
↑	L	L	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
↓	L	L	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
↓	L	H	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
↑	H	L	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}
↑	H	H	X	X	X	X	X	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}

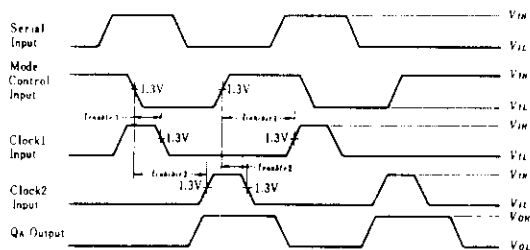
- Notes)
1. H; high level, L; low level, X; irrelevant
 2. †; transition from low to high level
 3. ‡; transition from high to low level
 4. a~d; the level of steady-state input at inputs A, B, C, or D, respectively
 5. $Q_{A0} \sim Q_{D0}$; the level of Q_A , Q_B , Q_C , or Q_D , respectively,

before the indicated steady-state input conditions were established.

6. $Q_{An} \sim Q_{Dn}$; the level of Q_A , Q_B , Q_C , or Q_D , respectively, before the most-recent (†) transition of the clock.
7. ‡; Shifting left requires external connection of Q_B to A, Q_C to B, and Q_D to C. Serial data is entered at input D.

RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
Clock frequency	f_{clock}	0	—	25	MHz
Clock pulse width	$t_{w(CK)}$	25	—	—	ns
Setup time	t_{su}	20	—	—	ns
Hold time	t_h	10	—	—	ns
Enable time 1	$t_{enable\ 1}$	20	—	—	ns
Enable time 2	$t_{enable\ 2}$	20	—	—	ns
Inhibit time 1	$t_{inhibit\ 1}$	20	—	—	ns
Inhibit time 2	$t_{inhibit\ 2}$	20	—	—	ns



Clock Enable/Inhibit Times

ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ*	max	Unit
Input voltage	V_{IH}		2.0	—	—	V
	V_{IL}		—	—	0.8	
Output voltage	V_{OH}	$V_{CC} = 4.75\text{V}, V_{IH} = 2\text{V}, V_{IL} = 0.8\text{V}, I_{OH} = -400\mu\text{A}$	2.7	—	—	V
	V_{OL}	$V_{CC} = 4.75\text{V}, V_{IH} = 2\text{V}, I_{OL} = 4\text{mA}$	—	—	0.4	V
		$V_{IL} = 0.8\text{V}, I_{OL} = 8\text{mA}$	—	—	0.5	
Input current	I_{IH}	$V_{CC} = 5.25\text{V}, V_i = 2.7\text{V}$	—	—	20	μA
	I_{IL}	$V_{CC} = 5.25\text{V}, V_i = 0.4\text{V}$	—	—	-0.4	mA
	I_i	$V_{CC} = 5.25\text{V}, V_i = 7\text{V}$	—	—	0.1	mA
Short-circuit output current	I_{os}	$V_{CC} = 5.25\text{V}$	-20	—	-100	mA
Supply current **	I_{CC}	$V_{CC} = 5.25\text{V}$	—	13	21	mA
Input clamp voltage	V_{IK}	$V_{CC} = 4.75\text{V}, I_{IN} = -18\text{mA}$	—	—	-1.5	V

* $V_{CC} = 5\text{V}, T_a = 25^\circ\text{C}$

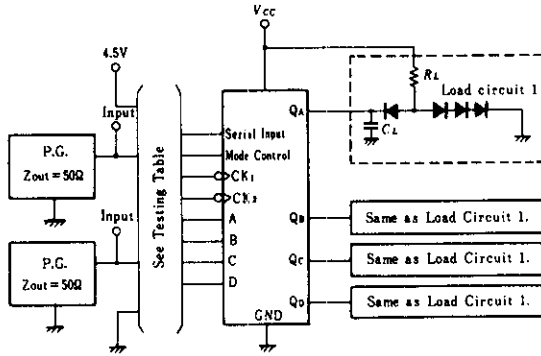
** I_{CC} is measured with all outputs and serial input open; A, B, C, and D inputs grounded; mode control at 4.5V; and momentary 3V, then ground, applied both clock inputs.

SWITCHING CHARACTERISTICS ($V_{CC} = 5\text{V}, T_a = 25^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ	max	Unit
Maximum clock frequency	f_{max}	$C_L = 15\text{pF}, R_L = 2\text{k}\Omega$	25	36	—	MHz
Propagation delay time	t_{PLH}		—	18	27	ns
	t_{PHL}		—	21	32	ns

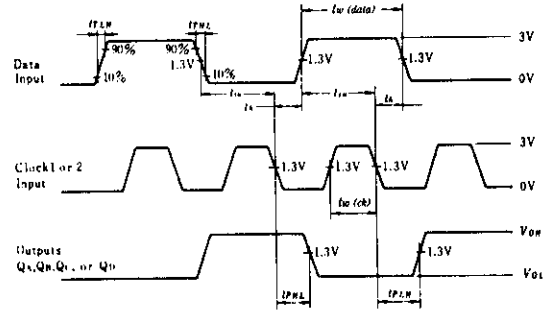
TESTING METHOD

1) Test Circuit



- Notes) 1. C_L includes probe and jig capacitance.
2. All diodes are 1S2074 P .

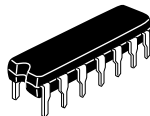
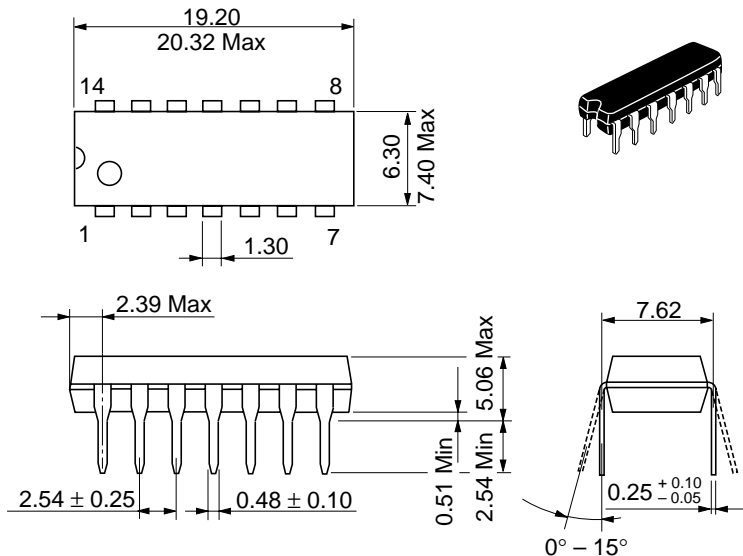
Waveform



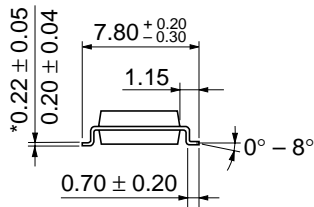
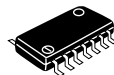
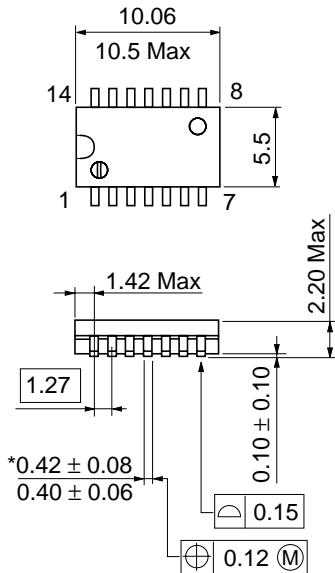
- Note) 1. Input pulse: $t_{PLH}, t_{PHL} \leq 10\text{ns}$,
Data $PRR = 500\text{kHz}$
Clock $PRR = 1\text{MHz}$

2) Testing Table

Item	From input to output	Inputs								Outputs			
		CK-1	CK-2	Mode Control	Serial Inputs	A	B	C	D	QA	QB	QC	QD
f_{max}	CK-1 → Q	IN	4.5V	0V	IN	4.5V	4.5V	4.5V	4.5V	OUT	OUT	OUT	OUT
	CK-2 → Q	4.5V	IN	4.5V	4.5V	IN	IN	IN	IN	OUT	OUT	OUT	OUT
t_{PLH}	CK-1 → Q	IN	4.5V	0V	IN	4.5V	4.5V	4.5V	4.5V	OUT	OUT	OUT	OUT
t_{PHL}	CK-2 → Q	4.5V	IN	4.5V	4.5V	IN	IN	IN	IN	OUT	OUT	OUT	OUT

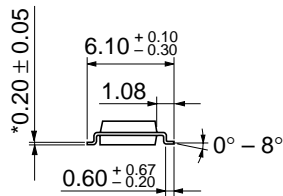
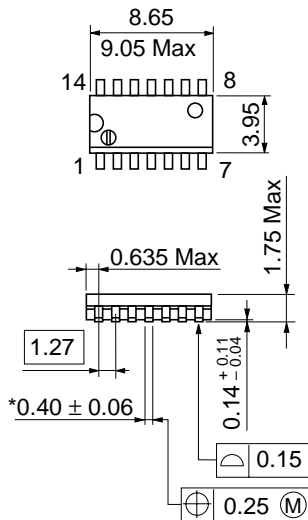


Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g



Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

Cautions

1. Hitachi neither warrants nor grants licenses of any rights of Hitachi's or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Hitachi bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
3. Hitachi makes every attempt to ensure that its products are of high quality and reliability. However, contact Hitachi's sales office before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
4. Design your application so that the product is used within the ranges guaranteed by Hitachi particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Hitachi bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as fail-safes, so that the equipment incorporating Hitachi product does not cause bodily injury, fire or other consequential damage due to operation of the Hitachi product.
5. This product is not designed to be radiation resistant.
6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Hitachi.
7. Contact Hitachi's sales office for any questions regarding this document or Hitachi semiconductor products.

HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL	NorthAmerica	: http://semiconductor.hitachi.com/
	Europe	: http://www.hitachi-eu.com/hel/ecg
	Asia (Singapore)	: http://www.has.hitachi.com.sg/grp3/sicd/index.htm
	Asia (Taiwan)	: http://www.hitachi.com.tw/E/Product/SICD_Frame.htm
	Asia (HongKong)	: http://www.hitachi.com.hk/eng/bo/grp3/index.htm
	Japan	: http://www.hitachi.co.jp/Sicd/indx.htm

For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose, CA 95134 Tel: <1> (408) 433-1990 Fax: <1> (408) 433-0223	Hitachi Europe GmbH Electronic components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322
--	---

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

Copyright ' Hitachi, Ltd., 1999. All rights reserved. Printed in Japan.